Abstracts

A CAD algorithm for coupling between dielectric covered MMICs in multi-chip assemblies

Z. Wang and R.W. Jackson. "A CAD algorithm for coupling between dielectric covered MMICs in multi-chip assemblies." 1998 MTT-S International Microwave Symposium Digest 98.1 (1998 Vol. I [MWSYM]): 33-37.

An algorithm is presented for determining the coupling between sealant covered MMICs in a multi-chip module. This technique is computationally simple, appropriate for use with layout based circuit CAD software, and uses no numerical electromagnetics. It has been tested by comparison to fullwave electromagnetic simulation.

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